



Customer Number 22,852  
Attorney Docket No. 04329.2583

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: Mika KIRITANI )

Serial No.: 09/887,104 )

Group Art Unit: 1722 )

Filed: June 25, 2001 )

For: SEMICONDUCTOR RESIN MOLD )  
AND SEMICONDUCTOR RESIN )  
MOLDING METHOD USING THE )  
MOLD )

**RECEIVED**

OCT 24 2001

**TC 1700**

Assistant Commissioner for Patents  
Washington, DC 20231

Sir:

CLAIM FOR PRIORITY

Under the provisions of Section 119 of 35 U.S.C., applicant hereby claims the benefit of Japanese Patent Application No. 2001-188772, filed June 21, 2001, for the above identified United States Patent Application.

Respectfully submitted,  
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Dated: October 22, 2001

By: 

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